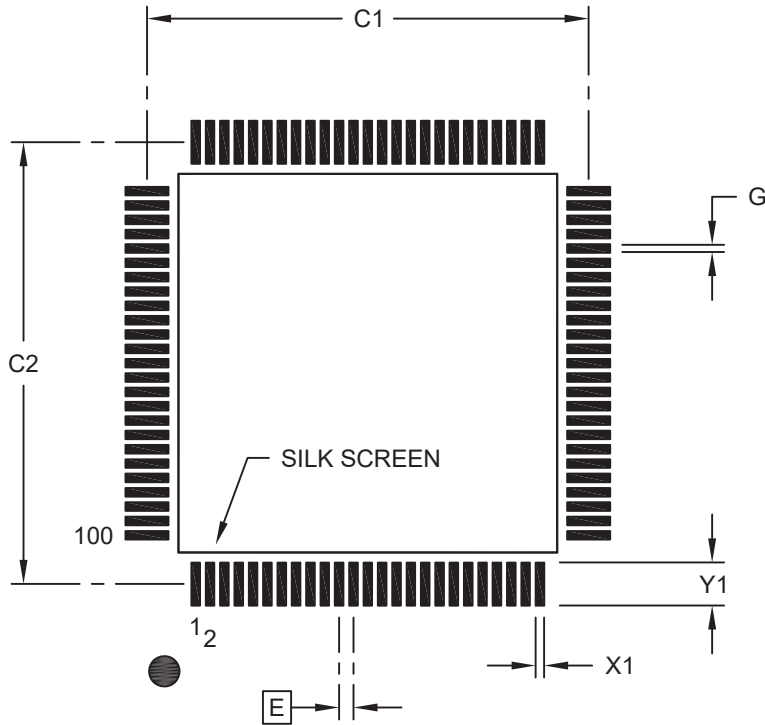


100-Lead Plastic Thin Quad Flatpack (E5X) - 14x14x1 mm Body [TQFP]; With 2.00 mm Footprint

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Contact Pitch	E		0.50 BSC		
Contact Pad Spacing	C1			15.40	
Contact Pad Spacing	C2			15.40	
Contact Pad Width (X100)	X1				0.30
Contact Pad Length (X100)	Y1				1.50
Contact Pad to Contact Pad (X96)	G	0.20			

Notes:

- Dimensioning and tolerancing per ASME Y14.5M.
BSC: Basic Dimension. The theoretically exact value is shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during the reflow process.